



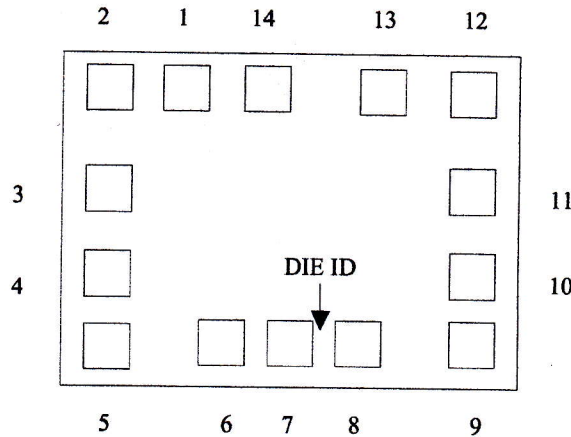
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PAD FUNCTIONS

- 1 A1
- 2 Y1
- 3 A2
- 4 Y2
- 5 A3
- 6 Y3
- 7 GND
- 8 Y4
- 9 A4
- 10 Y5
- 11 A5
- 12 Y6
- 13 A6
- 14 V_{cc}



The information provided here is believed to be correct at the date of issue.

Customers are advised to verify the accuracy of this information prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Back connection is the potential to which the substrate or bulk silicon may be connected. On some devices the substrate potential is maintained by electrical connection via a bond pad.

Note: 1 mil = 0.001inch

<u>APPROVED</u> GB DATE: 05/10/2007	54HC04 FAIRCHILD SEMICONDUCTOR	<u>DIE INFORMATION</u> DIMENSIONS (Mils): 29 x 22 x 14 BOND PADS (Mils): 3.5 x 3.5 min. MASK REF: DIE ID: HC04X BACK CONNECTION: FLOATING
DG 10.1.2 Rev B, 7/19/02		<u>METALLISATION</u> TOP: Al BACK: Si